

# MM3ZxxxST1G Series, SZMM3ZxxxST1G Series

## Zener Voltage Regulators

### 200 mW SOD-323 Surface Mount Tight Tolerance Portfolio

This series of Zener diodes is packaged in a SOD-323 surface mount package that has a power dissipation of 200 mW. They are designed to provide voltage regulation protection and are especially attractive in situations where space is at a premium. They are well suited for applications such as cellular phones, hand-held portables, and high density PC boards.

#### Specification Features

- Standard Zener Breakdown Voltage Range – 3.3 V to 36 V
- Steady State Power Rating of 200 mW
- Small Body Outline Dimensions:  
– 0.067" x 0.049" (1.7 mm x 1.25 mm)
- Low Body Height: 0.035" (0.9 mm)
- Package Weight: 4.507 mg/unit
- ESD Rating of Class 3 (> 16 kV) per Human Body Model
- Tight Tolerance  $V_Z$
- SZ Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant\*

#### Mechanical Characteristics:

**CASE:** Void-free, transfer-molded plastic

**FINISH:** All external surfaces are corrosion resistant

**MAXIMUM CASE TEMPERATURE FOR SOLDERING PURPOSES:**  
260°C for 10 Seconds

**LEADS:** Plated with Pb-Sn or Sn only (Pb-Free)

**POLARITY:** Cathode indicated by polarity band

**FLAMMABILITY RATING:** UL 94 V-0

**MOUNTING POSITION:** Any

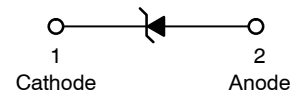


ON Semiconductor®

<http://onsemi.com>



SOD-323  
CASE 477  
STYLE 1



#### MARKING DIAGRAM



XX = Specific Device Code  
M = Date Code\*  
▪ = Pb-Free Package

(Note: Microdot may be in either location)

\*Date Code orientation may vary depending upon manufacturing location.

#### ORDERING INFORMATION

Device	Package	Shipping†
MM3ZxxxST1G	SOD-323 (Pb-Free)	3,000 / Tape & Reel
SZMM3ZxxxST1G	SOD-323 (Pb-Free)	3,000 / Tape & Reel
MM3ZxxxST3G	SOD-323 (Pb-Free)	10,000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### DEVICE MARKING INFORMATION

See specific marking information in the device marking column of the Electrical Characteristics table on page 3 of this data sheet.

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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### MAXIMUM RATINGS

Rating	Symbol	Max	Unit
Total Device Dissipation FR-5 Board, (Note 1) @ $T_A = 25^\circ\text{C}$ Derate above $25^\circ\text{C}$	$P_D$	200 1.5	mW mW/ $^\circ\text{C}$
Thermal Resistance from Junction-to-Ambient	$R_{\theta JA}$	635	$^\circ\text{C}/\text{W}$
Junction and Storage Temperature Range	$T_J, T_{stg}$	-65 to +150	$^\circ\text{C}$

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

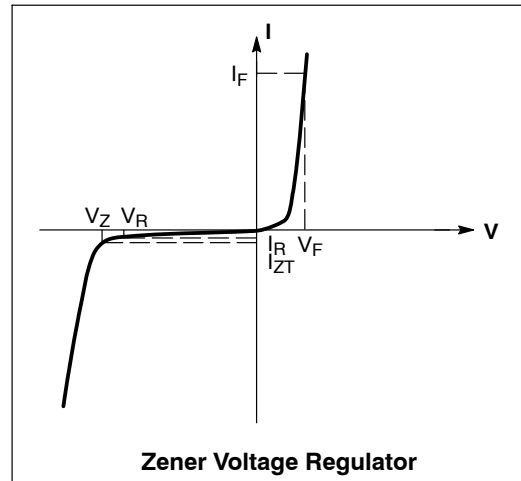
- FR-4 Minimum Pad.

### ELECTRICAL CHARACTERISTICS

( $T_A = 25^\circ\text{C}$  unless otherwise noted,

$V_F = 0.9\text{ V Max.}$  @  $I_F = 10\text{ mA}$  for all types)

Symbol	Parameter
$V_Z$	Reverse Zener Voltage @ $I_{ZT}$
$I_{ZT}$	Reverse Current
$Z_{ZT}$	Maximum Zener Impedance @ $I_{ZT}$
$I_{ZK}$	Reverse Current
$Z_{ZK}$	Maximum Zener Impedance @ $I_{ZK}$
$I_R$	Reverse Leakage Current @ $V_R$
$V_R$	Reverse Voltage
$I_F$	Forward Current
$V_F$	Forward Voltage @ $I_F$
$\Theta V_Z$	Maximum Temperature Coefficient of $V_Z$
C	Max. Capacitance @ $V_R = 0$ and $f = 1\text{ MHz}$



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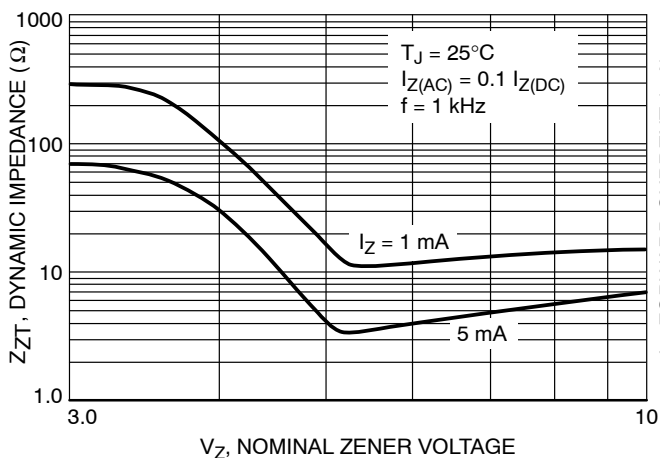
**ELECTRICAL CHARACTERISTICS** ( $V_F = 0.9 \text{ Max}$  @  $I_F = 10 \text{ mA}$  for all types)

Device*	Device Marking	Test Current $I_{zt}$ mA	Zener Voltage VZ		$Z_{zk} I_z = 0.5 \text{ mA } \Omega \text{ Max}$	$Z_{zt} I_z = I_{zt} @ 10\% \text{ Mod } \Omega \text{ Max}$	Max IR @ VR		$dV_z/dt$ (mV/k) @ $I_{zt1} = 5 \text{ mA}$		C pF Max @ $V_R = 0$ f = 1 MHz
			Min	Max			$\mu\text{A}$	V	Min	Max	
MM3Z3V0ST1G	T4	5.0	2.90	3.11	1000	100	10	1.0	-3.5	0	450
MM3Z3V3ST1G	T5	5.0	3.32	3.53	1000	95	5.0	1.0	-3.5	0	450
MM3Z3V9ST1G	T7	5.0	3.89	4.16	1000	90	3.0	1.0	-3.5	-2.5	450
MM3Z4V3ST1G	T8	5.0	4.17	4.43	1000	90	3.0	1.0	-3.5	0	450
MM3Z4V7ST1G	T9	5.0	4.55	4.75	800	80	3.0	2.0	-3.5	0.2	260
MM3Z5V1ST1G	TA	5.0	4.98	5.2	500	60	2.0	2.0	-2.7	1.2	225
MM3Z5V6ST1G	TC	5.0	5.49	5.73	200	40	1.0	2.0	-2.0	2.5	200
MM3Z6V2ST1G	TE	5.0	6.06	6.33	100	10	3.0	4.0	0.4	3.7	185
MM3Z6V8ST1G	TF	5.0	6.65	6.93	160	15	2.0	4.0	1.2	4.5	155
MM3Z7V5ST1G	TG	5.0	7.28	7.6	160	15	1.0	5.0	2.5	5.3	140
MM3Z8V2ST1G	TH	5.0	8.02	8.36	160	15	0.7	5.0	3.2	6.2	135
MM3Z9V1ST1G	TK	5.0	8.85	9.23	160	15	0.5	6.0	3.8	7.0	130
MM3Z10VST1G	WB	5.0	9.80	10.20	160	15	0.5	6.0	4.5	8.0	130
MM3Z12VST1G	TN	5.0	11.74	12.24	80	25	0.1	8.0	6.0	10	130
MM3Z13VST1G	TQ	5.0	12.91	13.49	160	30	0.1	8.0	7.0	11	120
MM3Z15VST1G	TP	5.0	14.34	14.98	80	40	0.1	11	8.8	12.7	130
MM3Z16VST1G	TU	5.0	15.85	16.51	80	40	0.05	11.2	10.4	14	105
MM3Z18VST1G	TW	5.0	17.56	18.35	80	45	0.05	12.6	12.4	16	100
MM3Z22VST1G	WP	5.0	21.54	22.47	100	55	0.05	15.4	16.4	20	85
MM3Z24VST1G	WT	5.0	23.72	24.78	120	70	0.05	16.8	18.4	22	80
MM3Z27VST1G	WQ	5.0	26.19	27.53	300	80	0.05	18.9	21.4	25.3	70
MM3Z30VST1G	WV	5.0	29.19	30.69	300	80	0.05	21.0	24.4	29.4	70
MM3Z33VST1G	WR	5.0	32.15	33.79	300	80	0.05	23.2	27.4	33.4	70
MM3Z36VST1G	WU	5.0	35.07	36.87	500	90	0.05	25.2	30.4	37.4	70
MM3Z39VST1G	WN	2.0	38.22	39.78	500	130	0.05	27.3	33.4	41.2	45

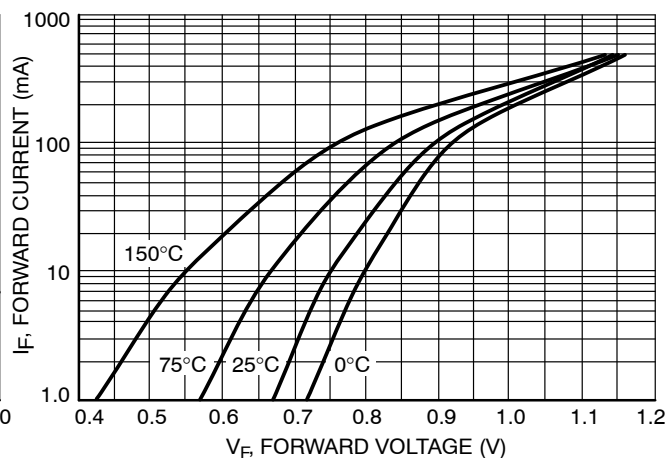
\*Include SZ-prefix devices where applicable.

# MM3ZxxxST1G Series, SZMM3ZxxxST1G Series

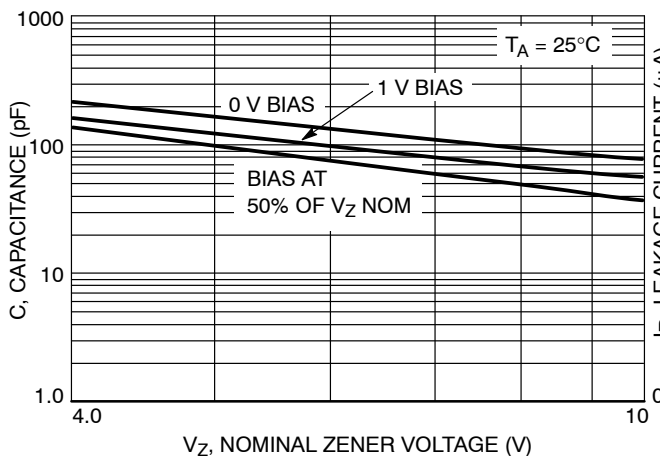
## TYPICAL CHARACTERISTICS



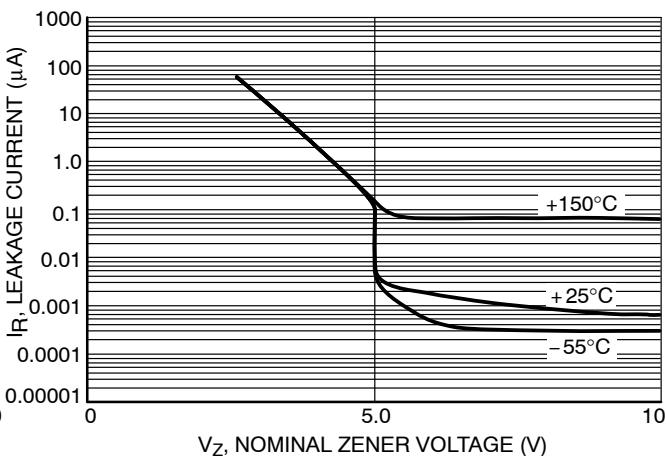
**Figure 1. Effect of Zener Voltage on Zener Impedance**



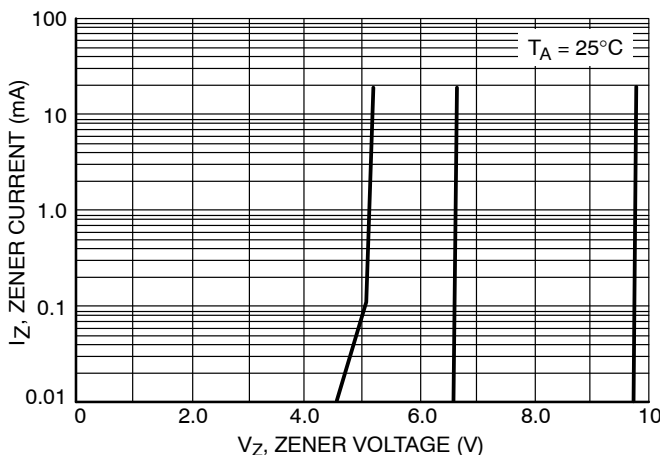
**Figure 2. Typical Forward Voltage**



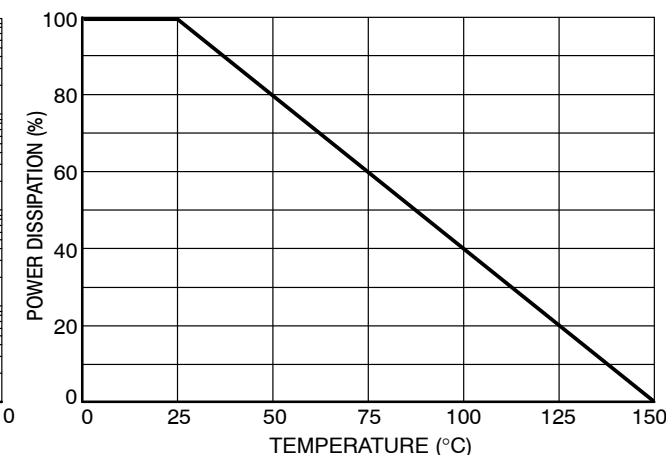
**Figure 3. Typical Capacitance**



**Figure 4. Typical Leakage Current**



**Figure 5. Zener Voltage versus Zener Current (V<sub>Z</sub> Up to 9 V)**

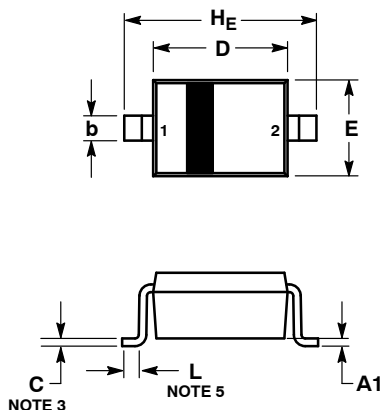


**Figure 6. Steady State Power Derating**

# MM3ZxxxST1G Series, SZMM3ZxxxST1G Series

## PACKAGE DIMENSIONS

SOD-323  
CASE 477-02  
ISSUE H



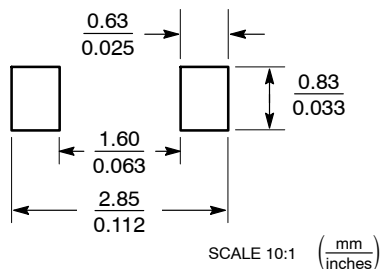
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. LEAD THICKNESS SPECIFIED PER L/F DRAWING WITH SOLDER PLATING.
4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
5. DIMENSION L IS MEASURED FROM END OF RADIUS.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.80	0.90	1.00	0.031	0.035	0.040
A1	0.00	0.05	0.10	0.000	0.002	0.004
A3	0.15 REF			0.006 REF		
b	0.25	0.32	0.4	0.010	0.012	0.016
C	0.089	0.12	0.177	0.003	0.005	0.007
D	1.60	1.70	1.80	0.062	0.066	0.070
E	1.15	1.25	1.35	0.045	0.049	0.053
L	0.08			0.003		
HE	2.30	2.50	2.70	0.090	0.098	0.105

STYLE 1:  
PIN 1. CATHODE  
2. ANODE

### SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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